

描述 / Descriptions

表面贴装快恢复二极管，反向电压：1000V，正向电流：3.0A，薄型 SMBF 封装。
Surface Mount Fast Recovery Rectifiers, Reverse Voltage:1000V, Forward Current:3.0A, SMBF thin package.

特征 / Features

玻璃钝化芯片，反向恢复时间快，无铅符合欧盟 RoHS 指令 2011/65/EU，适用于表面贴装。无卤产品。
Glass Passivated Chip Junction, Fast reverse recovery time, Lead free in comply with EU ROHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

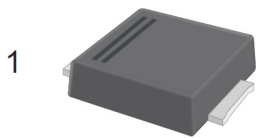
用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit



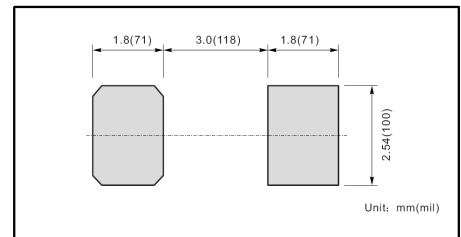
引脚排列 / Pinning



2

PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	参数符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current at $T_c = 100\text{ }^\circ\text{C}$	$I_F (AV)$	3.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	100	A
Typical Junction Capacitance ¹⁾	C_j	60	pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	45	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_j	-55~+150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55~+150	$^\circ\text{C}$

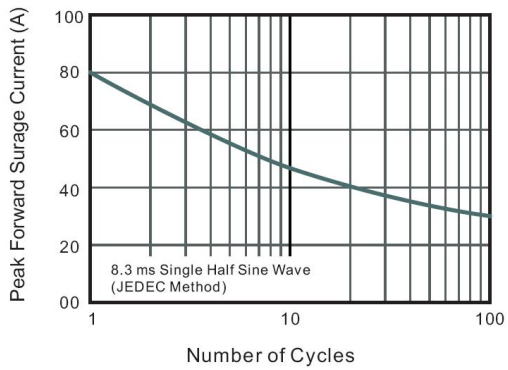
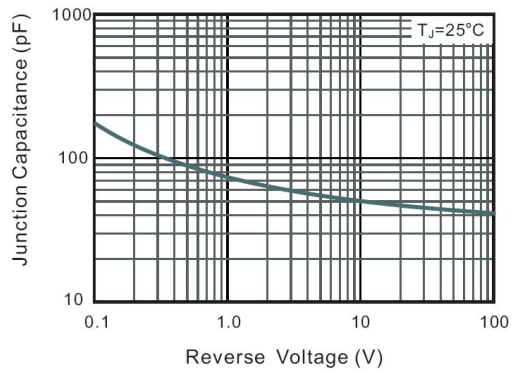
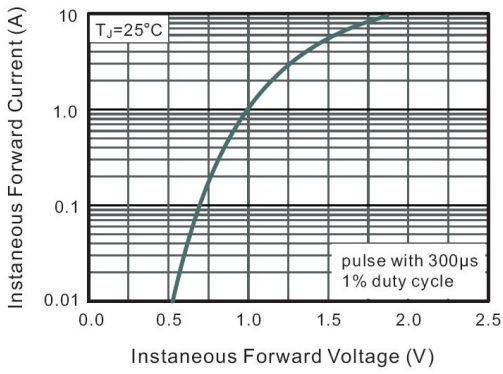
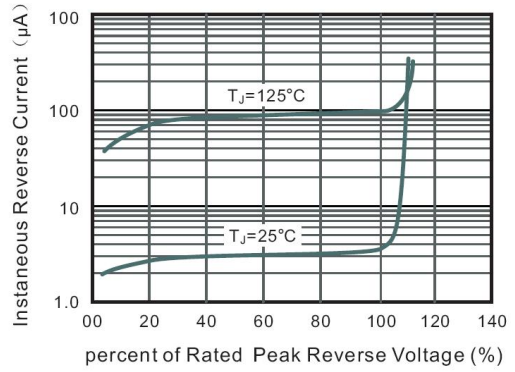
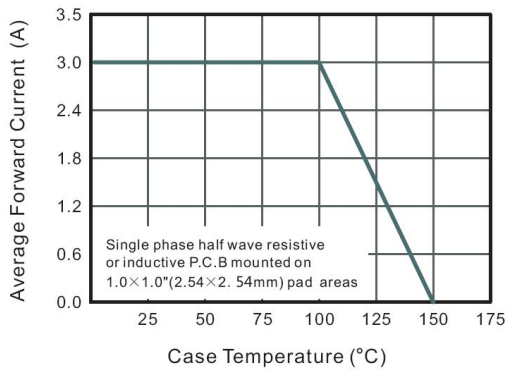
Note:

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
- 2) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

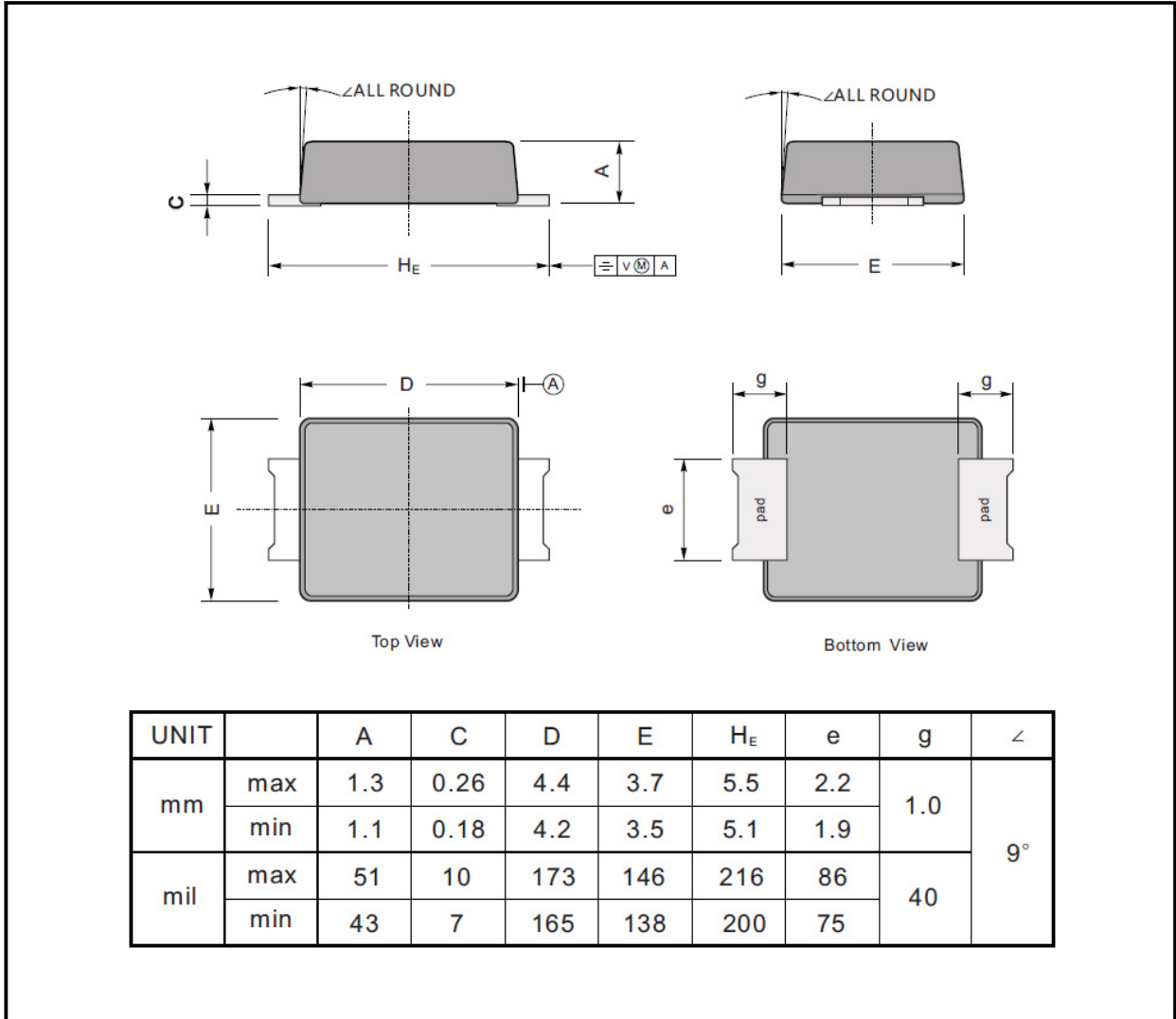
参数 Parameter	参数符号 Symbol	测试条件 Test condition	数值 Rating	单位 Unit
Maximum Instantaneous Forward Voltage	V_F	$I_F=3.0\text{A}$	1.3	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25\text{ }^\circ\text{C}$	5.0	μA
		$T_a=125\text{ }^\circ\text{C}$	150	
Maximum Reverse Recovery Time	t_{rr}	$I_F = 0.5\text{ A}$ $I_R = 1\text{ A}$ $I_{rr} = 0.25\text{ A}$	200	ns

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

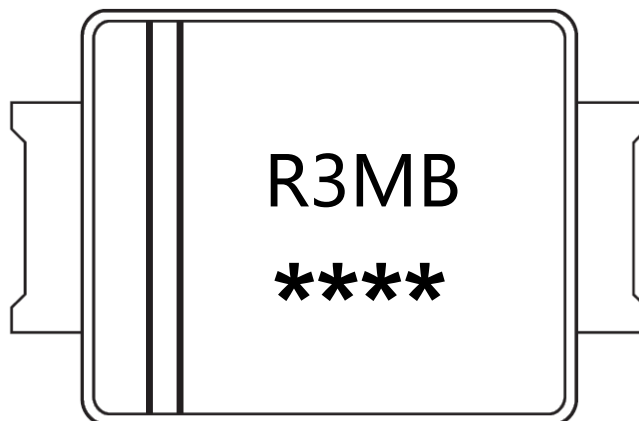
SMBF



印章说明 / Marking Instructions

Type number	Marking code
RS3MBF	R3MB

印章说明 / Marking Instructions



说明：

R3MB： 为型号代码

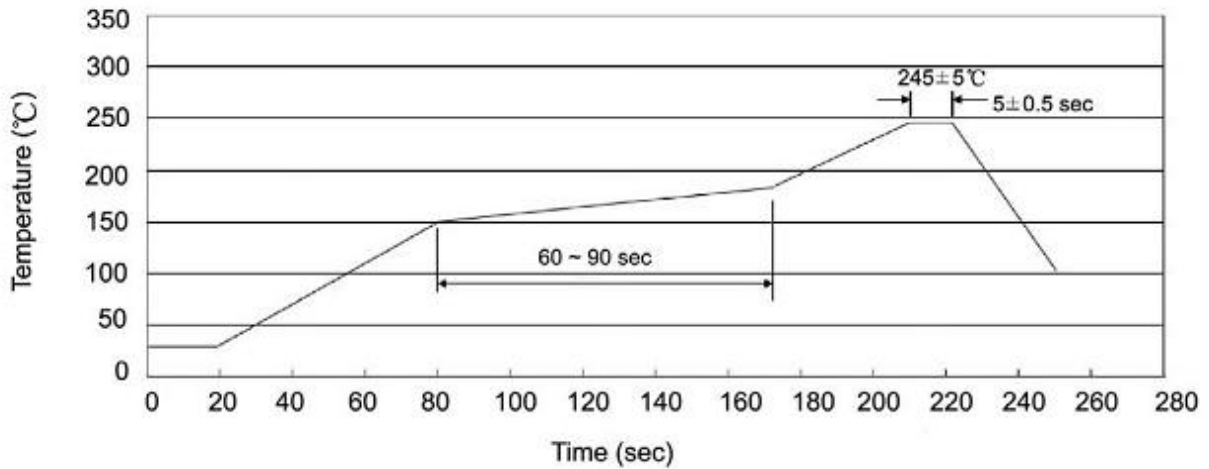
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

R3MB： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMBF	5000	2	10000	5	50000	13" ×15	336X332X40	380X335X366

使用说明 / Notices